

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L15	5654	Sumitomo.as. and (suspect\$4 holder chuck\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 12:34
L16	99	15 and ((ceramic "Al.sub.2O. sub.3" ("Al.sub.2" adj "O. sub.3")) same metal\$4 same (composit\$3 compound mix\$4 combinat\$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 12:35
L17	160	(suspect\$4 holder chuck\$3). clm. and ((ceramic "Al.sub.2O. sub.3" ("Al.sub.2" adj "O. sub.3")) same metal\$4 same (composit\$3 compound mix\$4 combinat\$3)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 12:36
L18	81	16 and (substrate wafer carrier) and heat\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 12:37
L19	41	17 and ((substrate wafer carrier) and heat\$3).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 12:37
L20	50	18 and (@ad<"20030605" @rlad<"20030605")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 12:38
L21	50	(US-20050089436-\$ or US-20050025654-\$ or US-20030221854-\$ or US-20030123213-\$ or US-20030089687-\$ or US-20030085206-\$ or US-20030071260-\$ or US-20030066608-\$ or US-20030066587-\$ or US-20030029569-\$ or US-20020185488-\$ or US-20020051353-\$ or US-20020034651-\$ or US-20010001622-\$).did. or (US-6768079-\$ or US-6693789-\$ or US-7211153-\$ or US-7090423-\$ or US-6950297-\$ or US-6881048-\$ or US-6872908-\$ or	US-PGPUB; USPAT	OR	OFF	2008/03/28 12:52

		US-6814917-\$ or US-6800360-\$ or US-6770379-\$ or US-6737168-\$ or US-6724018-\$ or US-6689984-\$ or US-6664515-\$ or US-6544654-\$ or US-6534190-\$ or US-6444957-\$ or US-6423400-\$ or US-6388273-\$ or US-6383446-\$ or US-6345917-\$ or US-6220765-\$ or US-6183874-\$ or US-6183846-\$ or US-6074893-\$ or US-5871850-\$).did. or (US-5800152-\$ or US-5766751-\$ or US-5712030-\$ or US-5616423-\$ or US-5252543-\$ or US-5084265-\$ or US-5028583-\$ or US-4937226-\$ or US-4383957-\$ or US-4303442-\$).did.				
L22	50	21 and ((ceramic "Al.sub.2O. sub.3" ("Al.sub.2" adj "O. sub.3")) same metal\$4 same (composit\$3 compound mix\$4 combinat\$3))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 12:52
S1	1	"20040244695"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/09/14 20:20
S2	13	(("20020049389") or ("20010042512") or ("6558736") or ("6015465") or ("5609721") or ("5580822") or ("5420043") or ("5650361") or ("6376340") or ("4402994") or ("6107197") or ("6218301")). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2005/08/18 16:54
S3	3	S2 and holder and (metal\$3 and ceramic\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 16:57
S4	3	S2 and (suspect\$3 or holder) and (metal\$3 and ceramic\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 19:07
S5	516	substrate and chamber and ((hold\$3 or suspect\$3) with (ceramic and metal\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 21:06
S6	27	S5 and (modulus and (heat or thermal) and coefficien\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 19:10

S7	6	S6 and ((hold\$3 or suspect\$3 or electrode or cathod or anode) with (composit\$3 or composit\$3 or combinat\$3) with (meta\$3 and ceramic\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 19:12
S8	30	("4645218"   "5155652"   "5191506"   "5280156"   "5376213"   "5460684"   "5478429"   "5527584"   "5529657"   "5581874"   "5600530"   "5606484"   "5625526"   "5665260"   "5671116"   "5737178"   "5745331"   "5818693"   "5827585"   "5858100"   "5886863"   "5886864"   "5949650"   "5958813"   "5968273"   "5978202"   "5986747"   "6048434"   "6072685"   "6094334").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/18 20:18
S9	21	S6 not S7	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/18 20:18
S10	9	S9 and (young\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/18 20:24
S11	12	S9 not S10	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 20:25
S12	66	hashikura-manabu.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 21:05
S13	132	nakata-hirohiko.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 21:05
S14	59	kuibira-akira.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 21:06
S15	210	natsuhara-masuhiro.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 21:06
S16	277	S12 S13 S14 S15	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 21:06
S17	32	S16 and chamber and ((chuck \$3 or hold\$3 or suspect\$3) with (cerami\$3 and metal\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 21:08

S18	1	S17 and young\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 21:08
S19	14	S17 and ((chuck\$3 or hold\$3 or suspect\$3) with (cerami\$3 and metal\$3)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2005/08/18 21:08
S23	353	((substrate or wafer) near3 (suspect\$3 or holder or receiver or keep\$4) with (form \$3 or creat\$3 or manufactur \$4)) and (ceramic or "SiC" or "Al.sub.2O.sub.3" or "AIN" or "WC" or "BN") with (metal\$3 or "Al" or "Si" or "Cu") with (composit\$4 or compound or mix\$3 or mixtur\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/09 18:41
S24	42	S23 and modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/09 18:42
S25	39	S24 and (@ad<"20030605" or @rlad<"20030605")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/09 19:35
S26	26	S25 and sint\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/09 18:43
S27	23	S26 and (stand\$3 or support \$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/09 19:32
S28	16	S25 not S27	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/09 19:32
S29	268	(S23 not S25) and (@ad<"20030605" or @rlad<"20030605")	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/09/16 19:23
S30	180	S29 and (chamber or vessel)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/09 19:36
S31	8	S30 and sint\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/09 19:37

S32	3	"6508884"	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/10 15:33
S33	3	S32 and electrode	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/02/10 15:33
S36	108	(susceptor same (cermet (metal\$4 near2 matrix near2 composit\$3) (hybrid adj composit\$3) (composit\$4 with ceramic with metal\$4)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/15 17:37
S40	112	(susceptor same (cermet (metal\$4 near2 matrix near2 composit\$3) (hybrid adj composit\$3) ((composit\$4 mixture) with ceramic with metal\$4)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/15 18:45
S41	49	S40 and (semiconduct\$3 (liquid adj crystal\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/15 18:46
S42	45	S41 and (@ad< "20030605" @rlad< "20030605")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/15 17:39
S43	11	S42 and ((composit\$3 mixture) with uniform\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/15 17:43
S44	34	S42 not S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/15 17:44
S45	12	(US-20030085206-\$ or US- 20030064225-\$ or US- 20020084036-\$ or US- 20020036201-\$ or US- 20020006678-\$).did. or (US- 6891138-\$ or US-6768079-\$ or US-6693789-\$ or US-6554907-\$ or US-6486542-\$ or US- 6160244-\$).did. or (US- 20040042152-\$).did.	US-PGPUB; USPAT; DERWENT	OR	ON	2006/09/15 18:05

S46	12	S45 and (susceptor and (cermet (metal\$4 near2 matrix near2 composit\$3) (hybrid adj composit\$3) ((composit\$4 mixture) with ceramic with metal\$4)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/15 18:45
S47	12	S46 and (semiconduct\$3 (liquid adj crystal\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/15 18:47
S48	9	S47 and (sinter\$3 powder\$3 infiltrat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/15 18:48
S49	0	S48 and (sinter\$3 and infiltrat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/15 18:48
S50	9	S48 and (heat\$4 resist\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/15 19:37
S51	7	S50 and uniform	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/15 19:37
S52	20	(US-20020075624-\$ or US-20040244695-\$ or US-20040217105-\$ or US-20030079684-\$ or US-20030064225-\$).did. or (US-5886863-\$ or US-5580822-\$ or US-5420043-\$ or US-6693789-\$ or US-6490146-\$ or US-6094334-\$ or US-5625526-\$ or US-6486542-\$ or US-6475606-\$ or US-6693790-\$ or US-6508884-\$ or US-6891138-\$ or US-6768079-\$ or US-6160244-\$).did. or (US-20040042152-\$).did.	US-PGPUB; USPAT; DERWENT	OR	ON	2006/09/16 19:02

S53	0	S52 and (infiltrat\$3 same (porous or pore or hole or void))	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/16 19:23
S54	0	S52 and (infiltrat\$3)	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/16 19:03
S55	3	S52 and (infiltrat\$3)	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/16 19:20
S56	77	((susceptor chuck) and (infiltrat\$3 with (composit\$4 cermet) with (ceramic insulat\$3 dielectric)))	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/16 19:22
S57	67	S56 and (infiltrat\$3 same (porous or pore or hole or void))	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/16 19:23
S58	55	S57 and (@ad<"20030605" or @rlad<"20030605")	US_PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/09/16 19:24
S59	46	S58 and uniform\$3	US_PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/09/16 19:24
S60	27	S59 and (ceramic with metal\$4 with composit\$3)	US_PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2006/09/16 19:25
S61	1	("6490146").PN.	US_PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/09/15 20:11
S62	1	S61 and (dielectric "115")	US_PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/15 20:12

S63	33	("4645218"   "5155652"   "5191506"   "5280156"   "5376213"   "5460684"   "5478429"   "5527584"   "5529657"   "5581874"   "5600530"   "5606484"   "5625526"   "5665260"   "5671116"   "5737178"   "5745331"   "5818693"   "5827585"   "5858100"   "5886863"   "5886864"   "5949650"   "5958813"   "5968273"   "5978202"   "5986747"   "6048434"   "6072685"   "6094334").PN. OR ("6490146").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/09/15 20:42
S64	1	("20030064225").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	OFF	2007/09/15 20:55
S65	1	S64 and (heat\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/15 21:02
S66	1	S64 and (heat\$3 with electric \$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/15 21:04
S67	1	S64 and (heat\$3 with (resist\$3 electric\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/15 21:05
S68	2	10/709889	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/15 23:01
S69	0	S68 and ((thermal\$3 heat\$3) near4 isolat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/15 23:03
S70	0	S68 and ((thermal\$3 heat\$3) with isolat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/15 23:03
S71	2	S68 and ((thermal\$3 heat\$3) same isolat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; IBM_TDB	OR	ON	2007/09/15 23:03
S72	843	361/234.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:14

S73	135	H02N13/00.ipc.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:14
S74	810	257/703.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:17
S75	131	257/648.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:19
S76	1029	H01L21/683.ipc.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:21
S77	2932	118/725.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:31
S78	4239	257/703,705,746,648,e29.075, e21.035,e21.203,e21.204, e39.009,e23.009,e23.112.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:34
S79	8998	S72 S73 S74 S75 S76 S77 S78	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:35
S80	3179	S79 and chamber	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:35
S81	2930	S79 and (suscept\$4 holder chuck\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:36
S82	1892	S80 and S81	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:36

S83	1809	S79 and (ceramic same metal \$4)	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:36
S84	785	S79 and (ceramic same metal \$4 same (composit\$3 compound mix\$4 combinat\$3))	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:37
S85	148	S82 and S84	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:38
S86	129	S85 and (@ad<"20040603" @rlad<"20040603")	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:38
S87	120	S85 and (@ad<"20030605" @rlad<"20030605")	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	OFF	2008/03/28 01:38

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